

Technology Capability

	DESCRIPTION	2020	2021
HDI	●組合層次 Stack-up	●5+N+5	●6+N+6
	●埋孔尺寸 Buried via hole size	●6.0mil (0.15mm)	●6.0mil (0.15mm)
	●盲孔尺寸 Blind via hole size	●3.0mil (0.076mm)	●3.0mil (0.076mm)
	●盲孔最大縱橫比 (Max.) aspect ratio for Blind Via hole	●1.0	●1.0
	●疊孔設計/ VIP Stack via / via in pad	●Yes	●Yes
	●填孔能力 Filled Via Capability	●Yes	●Yes